

DERWENT-ACC- 1989-230910**NO:****DERWENT- 198932****WEEK:****COPYRIGHT 1999 DERWENT INFORMATION LTD****TITLE:** Electrically conductive paste for joining mode chip to circuit board - comprises silver powder, epoxy! resin, hardener, curing accelerator and solvent**PATENT-ASSIGNEE: SUMITOMO BAKELITE CO[SUMB]****PRIORITY-DATA: 1987JP-0323703 (December 23, 1987)****PATENT-FAMILY:**

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 01165654 A	June 29, 1989	N/A	006	N/A
JP 94011842 B2	February 16, 1994	N/A	000	C08L 063/00

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
JP 01165654A	N/A	1987JP-0323703	December 23, 1987
JP 94011842B2	N/A	1987JP-0323703	December 23, 1987
JP 94011842B2	Based on	JP 1165654	N/A

INT-CL (IPC): C08K003/08, C08K007/06, C08K007/18, C08L063/00, C09D005/24, C09D163/00, H01B001/22**ABSTRACTED-PUB-NO: JP 01165654A****BASIC-ABSTRACT:**Paste comprises Ag powder, epoxy resin, hardener, curing accelerator and solvent.

The silver powder is a mixt. of 100 pts.wt. of flaky Ag powder, 5-70 pts. wt. of spherical Ag powder and 5-70 pts.wt. of dendritic Ag powder. The epoxy resin is liq. at normal temp.. The hardener is polyhydric phenol having at least 2.5 active H per molecule on average. The curing accelerator is a tert. amine or salt. the solvent is a glycol deriv.. The resin paste assumes the state of B stage. The spherical Ag powder has an average particle dia. of 0.1-2 micro -m.

ADVANTAGE - Resin paste has good adhesive property and consistent electrical conductivity and is useful for joining a diode chip to a circuit board and for liq. crystal board.

TITLE- ELECTRIC CONDUCTING PASTE JOIN MODE CHIP CIRCUIT BOARD COMPRISE SILVER POWDER
TERMS: POLYEPOXIDE RESIN HARDEN CURE ACCELERATE SOLVENT**DERWENT-CLASS: A21 A85 L03****CPI-CODES: A05-A01B1; A08-D01; A08-M09A; A08-R05; A09-A03; A12-E07; A12-L03B; A12-S; L03-A01A3;****POLYMER-MULTIPUNCH-CODES-AND-KEY-SERIALS:**